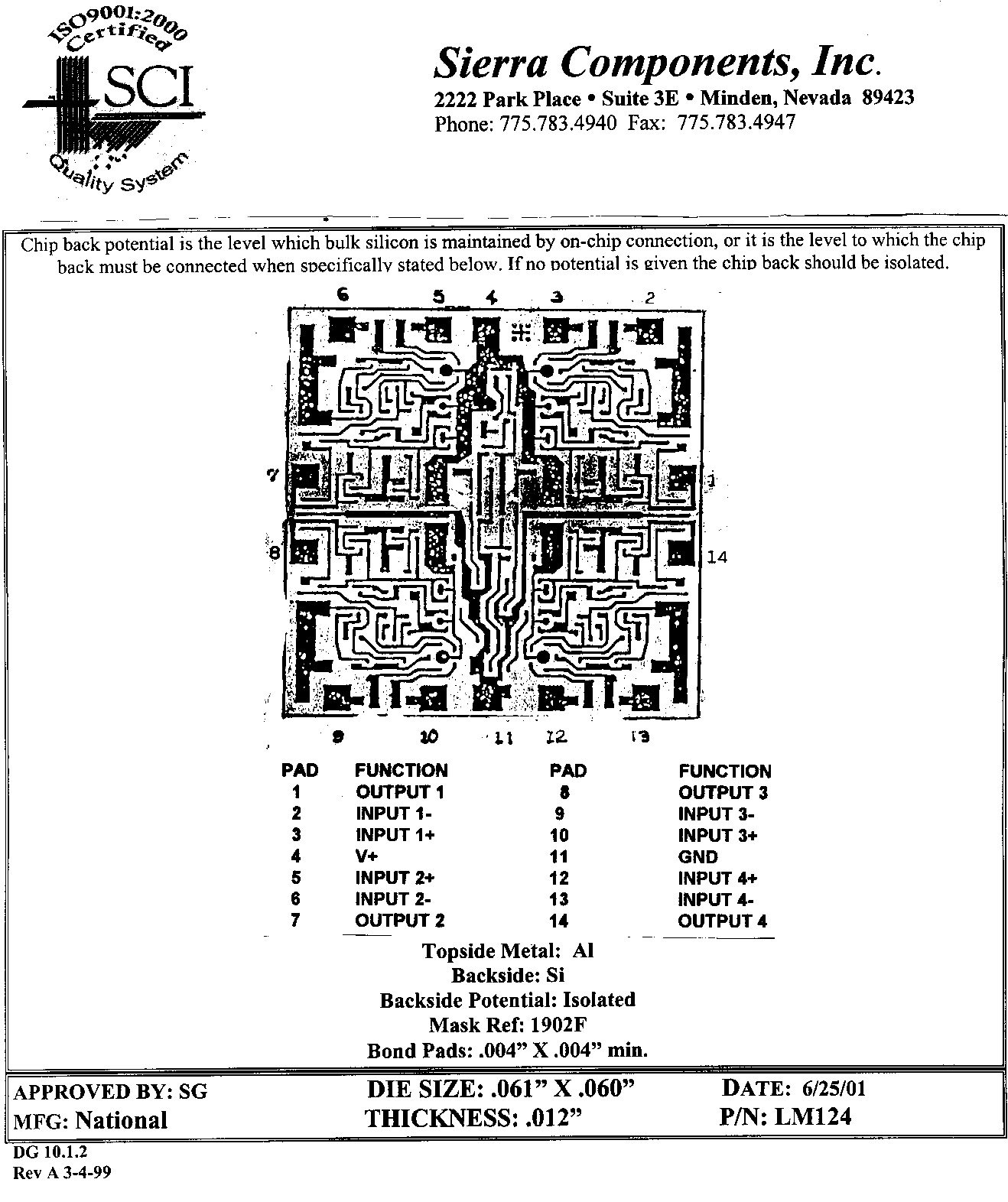
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **OUTPUT 1**
2. **INPUT 1 –**
3. **INPUT 1 +**
4. **V +**
5. **INPUT 2 +**
6. **INPUT 2 -**
7. **OUTPUT 2**
8. **OUTPUT 3**
9. **INPUT 3 -**
10. **INPUT 3 +**
11. **GND**
12. **INPUT 4 +**
13. **INPUT 4 –**
14. **OUTPUT 4**

**.061”**

****

**.060”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: ISOLATED**

**Mask Ref: 1902F**

**APPROVED BY: DK DIE SIZE .060” X .061” DATE: 7/11/22**

**MFG: NATIONAL/T.I. THICKNESS .000” P/N: LM124**

**DG 10.1.2**

#### Rev B, 7/1